

AMENDMENTS

Please amend the application as follows:

In the Specification:

Please amend the paragraph [0040] as follows:

In one exemplary embodiment, a eutectic-metal bond is formed between the gasket [[21]] 42 and pad 49. In particular, the layer 47 is composed of gold (Au). Further, a tin (Sn) layer is deposited on the pad 49. Then, the substrates 21 and 24 are pressed together and heated to a temperature that melts the tin causing the tin to diffuse with the gold layer 47. As a result, a gold-tin (Au-Sn) bond is formed between the pad 49 and the gasket 42. In other embodiments, other types of material may be used to form a eutectic-metal bond between components of the substrates 21 and 24, and other types of bonding techniques may be used to bond the substrates 21 and 24. Further, the substrates 21 and 24 may be bonded by bonding other components of the substrates 21 and 24, such as the posts 27 or other components not specifically shown in FIG. 1.